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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: **William James Palmteer and Philip Joseph Beuler**

Application No.: 09/966,222

Examiner: Unassigned

Filed: September 28, 2001

Group Art Unit: Unassigned

Docket No.: 17658

Title: **IMPROVED LEADFRAME-BASED CHIP SCALE PACKAGE**

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service on January 18, 2002, in an envelope as First Class Mail, postage prepaid, addressed to: Commissioner for Patents, Washington, D.C. 20231, ATTN: Official Draftsperson.

1-18-02
Date

Denise Grisack
Denise Grisack

TRANSMITTAL LETTER TO OFFICIAL DRAFTSPERSON

Commissioner for Patents
Washington, D.C. 20231

ATTN: Official Draftsperson

Sir:

Applicant encloses herewith three (3) sheets of formal drawings (Figures 1A through 3) relating to the above-identified patent application.

On the back of the enclosed drawings are: the Name of the first named inventor, the

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Application No. 09/966,222

Docket No. 17658 USA

Application No., and the attorney's name and phone number.

Please charge any comparison fees to Synnestvedt & Lechner's Deposit Account No. 19-

5425. Copies of this Transmittal Letter are attached in duplicate.

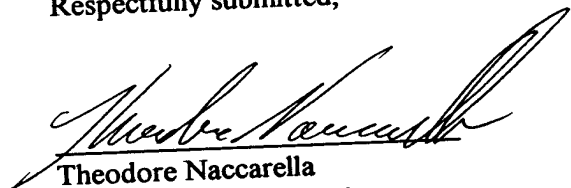
Please address all correspondence to:

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Telephone calls should be directed to Theodore Naccarella at (215) 923-4466

Respectfully submitted,

Dated: 1.18.02


Theodore Naccarella
Registration No. 33,023

Enclosures

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